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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/621,445	07/18/2003	Yasuo Yamagishi	030868	1112
23850	7590 11/07/200	5	EXAMINER	
ARMSTRO	NG, KRATZ, QUIN	HOLLINGTON, JERMELE M		
1725 K STRE	ET, NW		ART UNIT	PAPER NUMBER
SUITE 1000			7447 6747	
WASHINGTO	ON, DC 20006		2829	

DATE MAILED: 11/07/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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	•	Application No.	Applicant(s)			
Office Action Summary		10/621,445	YAMAGISHI ET AL.			
		Examiner	Art Unit	_		
		Jermele M. Hollington	2829	_		
Period fo	<ul> <li>The MAILING DATE of this communication ap r Reply</li> </ul>	pears on the cover sheet with	n the correspondence address			
WHIC - Exten after S - If NO - Failur Any re	DRTENED STATUTORY PERIOD FOR REPL HEVER IS LONGER, FROM THE MAILING D sions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. period for reply is specified above, the maximum statutory period e to reply within the set or extended period for reply will, by statutely received by the Office later than three months after the mailing d patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNIC. 136(a). In no event, however, may a rep will apply and will expire SIX (6) MONT e, cause the application to become ABA	ATION.  bly be timely filed  HS from the mailing date of this communication.  NDONED (35 U.S.C. § 133).			
Status						
1)⊠	Responsive to communication(s) filed on 19 C	October 2005.				
2a) <u></u> ☐	☐ This action is FINAL. 2b) ☑ This action is non-final.					
•	☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
	closed in accordance with the practice under	Ex parte Quayle, 1935 C.D.	11, 453 O.G. 213.			
Disposition	on of Claims		•			
5)⊠ 6)⊠ 7)□	Claim(s) <u>1-31</u> is/are pending in the application 4a) Of the above claim(s) <u>3,5,8,9 and 12-31</u> is Claim(s) <u>10 and 11</u> is/are allowed. Claim(s) <u>1-2, 4 and 6-7</u> is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/o	/are withdrawn from conside	· eration.			
, —	on Papers					
9)	The specification is objected to by the Examination of the drawing(s) filed on is/are: a) accomplicant may not request that any objection to the Replacement drawing sheet(s) including the correct the oath or declaration is objected to by the E	cepted or b) objected to be drawing(s) be held in abeyand ction is required if the drawing(s	e. See 37 CFR 1.85(a). i) is objected to. See 37 CFR 1.121(d).			
Priority u	nder 35 U.S.C. § 119					
12) 🔀 / a) [	Acknowledgment is made of a claim for foreign  All b) Some * c) None of:  1. Certified copies of the priority document  2. Certified copies of the priority document  3. Copies of the certified copies of the priority document application from the International Bureatee the attached detailed Office action for a list	nts have been received. Its have been received in Appority documents have been reau (PCT Rule 17.2(a)).	plication No eceived in this National Stage			
2) Notice 3) Inform	t(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08 r No(s)/Mail Date		/Mail Date ormal Patent Application (PTO-152)			

#### **DETAILED ACTION**

## Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claims 1-2 and 4 are rejected under 35 U.S.C. 102(e) as being anticipated by Eldridge et al (6727579).

Regarding claim 1, Eldridge et al disclose [see Fig. 33] a probe card (carrier assembly 3300) for testing a semiconductor chip (electronic component 3324) comprising: plurality of probes (resilient contact structure 3322); build-up interconnection layer (multi-layer substrate 3320) having a multilayer interconnection structure therein, said interconnection structure comprising plural interconnection layers [not number but shown] and one or more resin insulation layers (3320a) insulating said interconnection layers from each other, said build-up interconnection layer (3320) carrying said plurality of probes (3322) on a top surface thereof in electrical connection with said multilayer interconnection structure; and a decoupling capacitor (decoupling capacitor 3370) embedded resin insulation layer (3320a) constituting said build-up interconnection layer (3320) in electrical connection with one of said probes (3322) via said multilayer interconnection structure (3320), said multilayer interconnection structure (3320) including an inner via-contact (contact pads 3324) in the vicinity of said probe (3322).

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Regarding claim 2, Eldridge et al disclose said capacitor (3370) has a thickness generally equal to or less than a thickness of said resin insulation layer (3320).

Regarding claim 4, Eldridge et al disclose said capacitor (3370) is formed in said buildup interconnection layer (3320) right underneath one of said probes (3322).

### Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 5. Claims 6-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Eldridge et al (6727579) in view of Fukuzumi et al (6548844).

Regarding claim 6, Eldridge et al disclose [see Fig. 33] a probe card (3300) for testing a semiconductor chip (3302), comprising: a capacitor (3370) embedded resin insulation layer (3320a) constituting said build-up interconnection layer (3320) in electrical connection with one of said probes (3322) via said multilayer interconnection structure (3320). However, they do not

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disclose the feature of the capacitor as claimed. Fukuzumi et al disclose [Fig. 1] a capacitor structure 1 includes a dielectric film (capacitor dielectric film 3) of a complex oxide containing at least one metal element selected from the group consisting of Sr, Ba, Pb, Zr, Mg and Nb [see col. 5, lines 25-38]. Further, Fukuzumi et al teach that the addition of features of the capacitor is advantageous because it suppresses the deterioration of the data retaining characteristic that is originated from when annealing is performed in an atmosphere containing a reduce agent. It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the apparatus of Horel et al by adding the features of the capacitor as taught by Fukuzumi et al in order to suppress the deterioration of the data retaining characteristic that is originated from when annealing is performed in an atmosphere containing a reduce agent.

Regarding claim 7, Eldridge et al disclose [see Fig. 33] a probe card (3300) for testing a semiconductor chip (3302), comprising: a capacitor (3370) embedded resin insulation layer (3320a) constituting said build-up interconnection layer (3320) in electrical connection with one of said probes (3322) via said multilayer interconnection structure (3320). However, they do not disclose the feature of the capacitor as claimed. Fukuzumi et al disclose [Fig. 1] a capacitor structure 1 includes an upper (common electrode 4) and lower (dispersion electrode 2) electrodes sandwiching a dielectric film (capacitor dielectric film 3), said upper (4) and lower (2) electrodes containing at least one metal element or a metal oxide selected from the group consisting of Pt, Au, Cu, Pb, Ru, a Ru oxide, Ir, an Ir oxide, and Cr [see col. 5, lines 43-45 and col. 6, lines 8-25]. Further, Fukuzumi et al teach that the addition of features of the capacitor is advantageous because it suppresses the deterioration of the data retaining characteristic that is originated from when annealing is performed in an atmosphere containing a reduce agent. It would have been

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obvious to a person having ordinary skill in the art at the time the invention was made to modify the apparatus of Horel et al by adding the features of the capacitor as taught by Fukuzumi et al in order to suppress the deterioration of the data retaining characteristic that is originated from when annealing is performed in an atmosphere containing a reduce agent.

### Conclusion

#### Election/Restrictions

- 6. This application contains claims 12-31 drawn to an invention nonelected without traverse in Paper No. 12/1/04. A complete reply to the final rejection must include cancellation of nonelected claims or other appropriate action (37 CFR 1.144) See MPEP § 821.01.
- 7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Chraft et al (6911835) disclose different features of a capacitor for a semiconductor device.
- 8. Claims 10-11 are allowed over the prior art.
- 9. The following is a statement of reasons for the indication of allowable subject matter: regarding claim 10, the primary reason for the allowance of the claim is due to the specific limitation of a test method of a semiconductor device comprising the step of before contacting said probe card to said semiconductor chip, of setting an impedance between said probe and said capacitor to be substantially equal to an impedance of a semiconductor package including therein said semiconductor chip and a capacitor, for a part between said semiconductor chip and said capacitor. Since claim 11 depends from claim 10, it is also have allowable subject matter.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jermele M. Hollington whose telephone number is (571) 272-1960. The examiner can normally be reached on M-F (9:00-4:30 EST) First Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nestor Ramirez can be reached on (517) 272-2034. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jermele M. Hollington Primary Examiner Art Unit 2829

JMH November 2, 2005